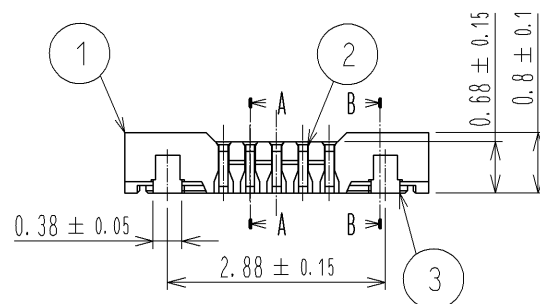
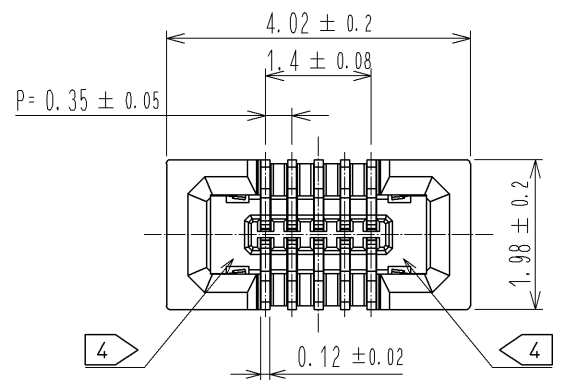
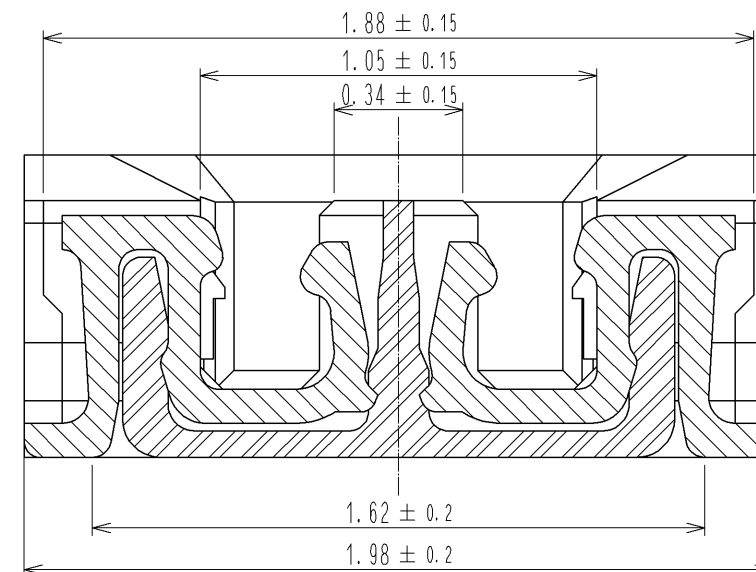
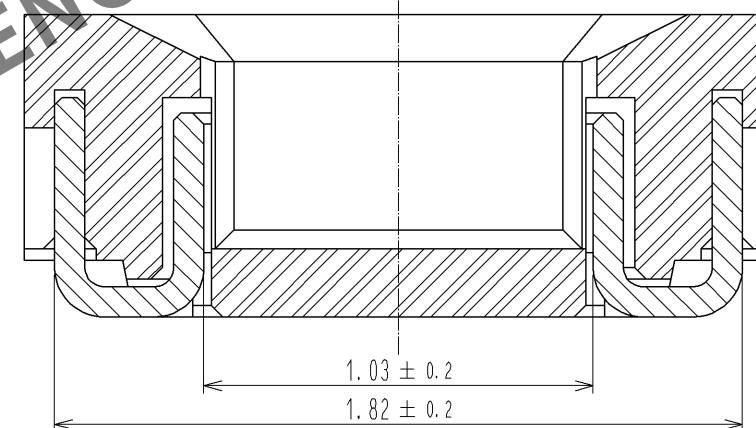


- NOTE) 1 . ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX
2 CONTACT PLATING SPECIFICATIONS.
CONTACT AREA : GOLD 0.05 μ m MIN
SMT LEAD : GOLD 0.05 μ m MIN
UNDERPLATING : NICKEL 1 μ m MIN
(SURFACE : SEALING)
3 REINFORCED METAL FITTINGS LOCK
SMT LEAD : GOLD 0.05 μ m MIN
UNDERPLATING : NICKEL 1 μ m MIN
(SURFACE : SEALING)
4 CAV NO. AND HRS MARK MAY BE INDICATED IN APPROX POSITION SHOWN.

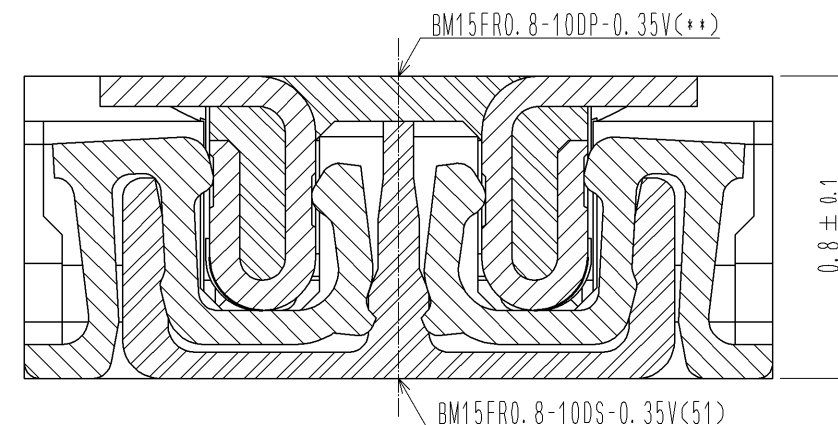
A-A (50:1)



B-B (50:1)

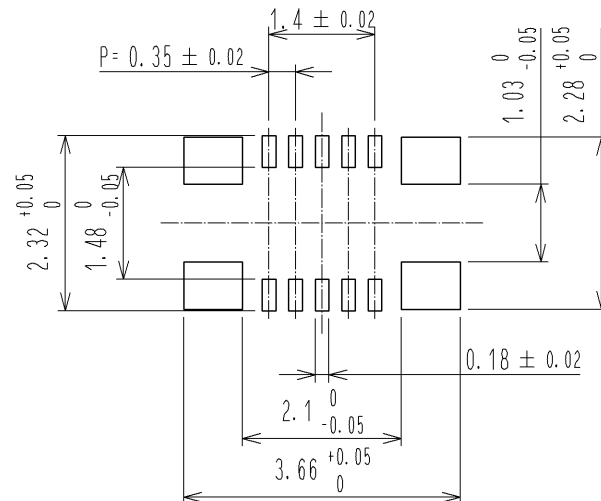


ENGAGEMENT FIGURE (50:1)



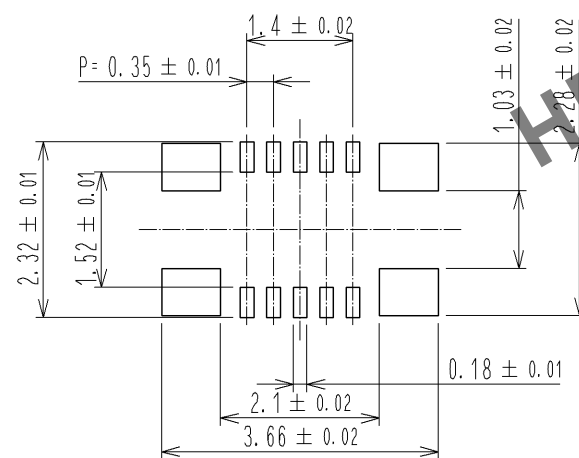
4	PS	CLEAR (ENBOSSED CARRIER TAPE)			
3	PHOSPHOR BRONZE	3	7	PS	CLEAR (REINFORCEMENT COLLAR)
2	PHOSPHOR BRONZE	2	6	PS	BLACK (PLASTIC REEL)
1	LCP	UL94 V-0, BLACK	5	POLYESTER	CLEAR (COVER TAPE)
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS
UNITS mm		SCALE 10 : 1	COUNT 1	DESCRIPTION OF REVISIONS	DESIGNED CHECKED DATE
		APPROVED : KH. IKEDA	13.12.13	DRAWING NO.	EDC3-355885-01
		CHECKED : YH. MICHIDA	13.12.12	PART NO.	BM15FR0.8-10DS-0.35V(51)
		DESIGNED : YK. KOBAYASHI	13.12.12	CODE NO.	CL673-1225-5-51
		DRAWN : YK. KOBAYASHI	13.12.12		

◆ RECOMMENDED PCB LAYOUT

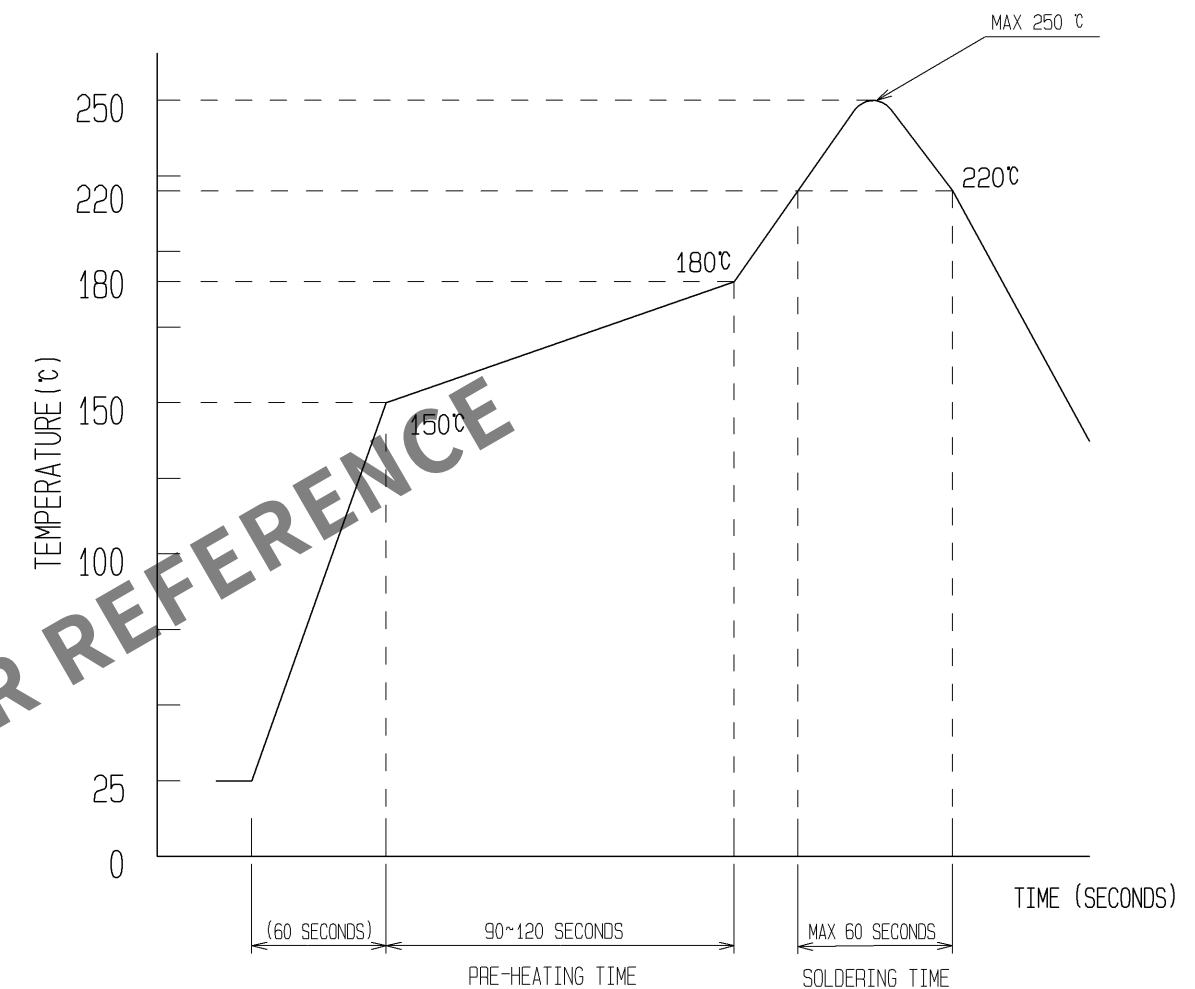


◆ RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : $100 \mu\text{m}$



5 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD: IR REFLOW

NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.

1) REFLOW TIME

DURATION ABOVE 220°C: 60 SEC. MAX.
(PEAK TEMPERATURE: 250°C MAX)

2) PRE-HEAT TIME

PRE-HEAT TEMPERATURE(MIN): 150°C
PRE-HEAT TEMPERATURE(MAX): 180°C
PRE-HEAT TIME: 90-120 sec.

5 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

HRS

DRAWING NO.	EDC3-355885-01
PART NO.	BM15FR0.8-10DS-0.35V<51>
CODE NO.	CL673-1225-5-51

2/3

